

PCN Number:	20220404000.1	PCN Date:	April 04, 2022
Title:	Qualification of UTL3 as an additional assembly site for select Devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	July 3, 2022	Estimated Sample Availability:	Date provided at sample request
Change Type:			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
PCN Details			
Description of Change:			
Texas Instruments Incorporated is announcing the qualification of UTL3 as an alternate Assembly site for devices listed below in the product affected section. There are no construction differences between the two sites			
Reason for Change:			
Supply continuity			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			
Impact on Environmental Ratings			
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.			
RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change
Changes to product identification resulting from this PCN:			
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
UTL1	NSE	THA	Bangkok
UTL3	UT3	THA	Bangpakong
Sample product shipping label (not actual product label)			
<p> TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750 (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS </p>			
Product Affected:			
DRV5032AJDMRR	DRV5032DUDMRR	DRV5032FADMRR	DRV5032FDDMRR
DRV5032AJDMRT	DRV5032DUDMRT	DRV5032FADMRT	DRV5032FDDMRT

Qualification Report
Approve Date 30-MARCH -2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DRV5032DUDMRR	Qual Device: DRV5032FDDMRR	Qual Device: DRV5032FADMRR	Qual Device: DRV5032AJDMRR
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	1/77/0	1/77/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	1/77/0	1/77/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/77/0	1/77/0	1/77/0	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	1/30/0	-	-	-

- QBS: Qual By Similarity
- Qual Device DRV5032DUDMRR is qualified at MSL1 260C
- Qual Device DRV5032FDDMRR is qualified at MSL1 260C
- Qual Device DRV5032FADMRR is qualified at MSL1 260C
- Qual Device DRV5032AJDMRR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-CHG-2108-069

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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